

View Online at https://aerobasegroup.com/nsn/5910-01-372-5333

Body Style: Chip type **Reliability Indicator:** Established **Reliability Failure Rate Level In Percent:** 0.010 **Terminal Length:** 0.010 inches **Body Length:** 0.055 inches **Body Width:** 0.055 inches **Body Height:** Between 0.020 inches and 0.057 inches Schematic Diagram Designator: No common or grounded electrode (s) Insulation Resistance At Maximum Operating Temp: 1000.0 megohms **Capacitance Value Per Section:** 6.200 picofarads single section Nonderated Operating Temp: Between -55.0 degrees celsius and 125.0 degrees celsius Tempurature Coefficient Of Capacitance Per Section In Ppm Per Deg Celsius: 0.0 single section Nonderated Continuous Voltage Rating And Type Per Section: 50.0 dc single section **Tolerance Range Per Section:** -0.10/+0.10 picofarads single section **Case Material:** Ceramic Insulation Resistance At Reference Temp: 100000.0 megohms **Dissipation Factor At Reference Tempurature In Percent:** 0.150 **Terminal Surface Treatment:** Solder **Test Data Document:** 81349-mil-c-55681 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification format; excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data on certain environmental and performance requirements and test conditions that are shown as "typical", "average", "", etc.). **Terminal Type And Quantity:**

2 bonding pad

Specification Data:

81349-mil-c-55681/4 government specification



Shelf Life:

N/a

Unit Of Measure:

Demilitarization:

No

Fiig:

A010b0